

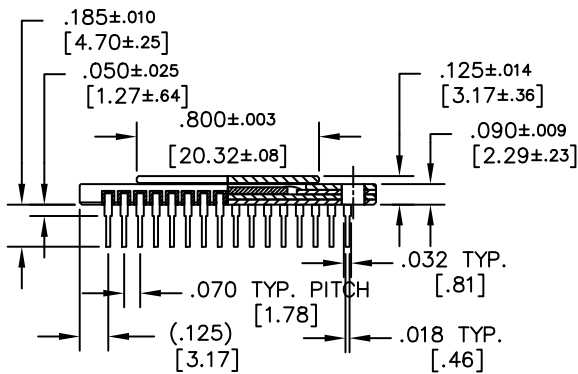
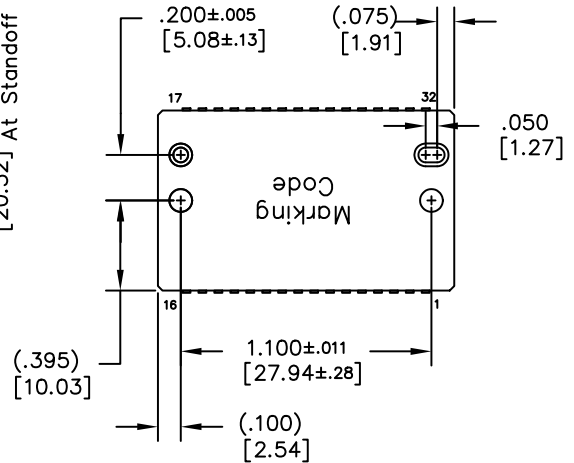
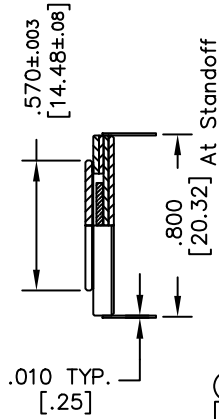
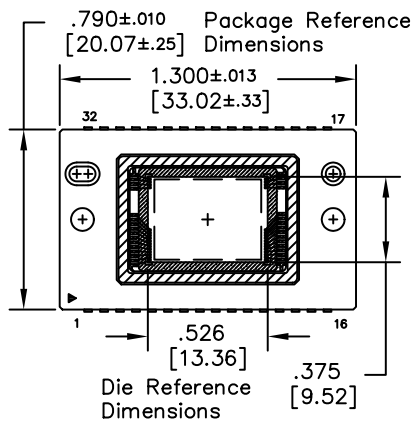
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



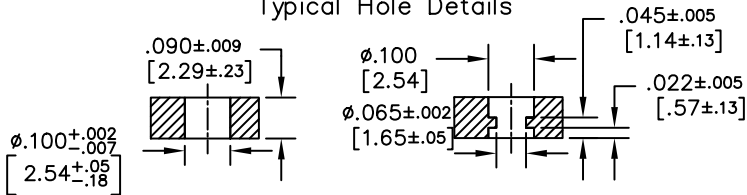
CERAMIC DIP 32, 33.02x20.07
CASE 125BD
ISSUE O

DATE 03 JUL 2014



NOTES:
 1. COVER GLASS IS MANUALLY PLACED AND VISUALLY ALIGNED OVER DIE – LOCATION ACCURACY IS NOT GUARANTEED.

Typical Hole Details

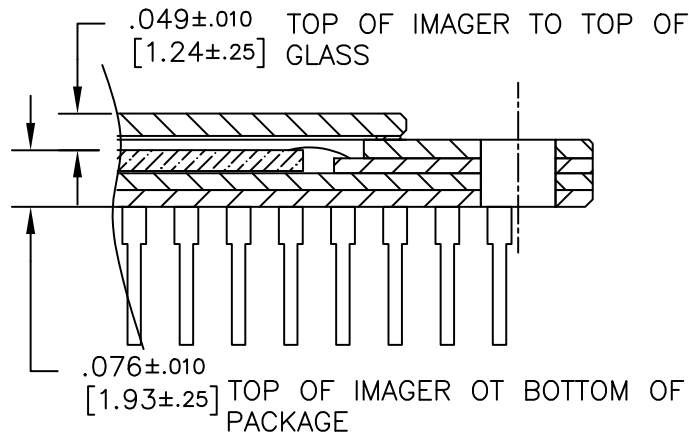
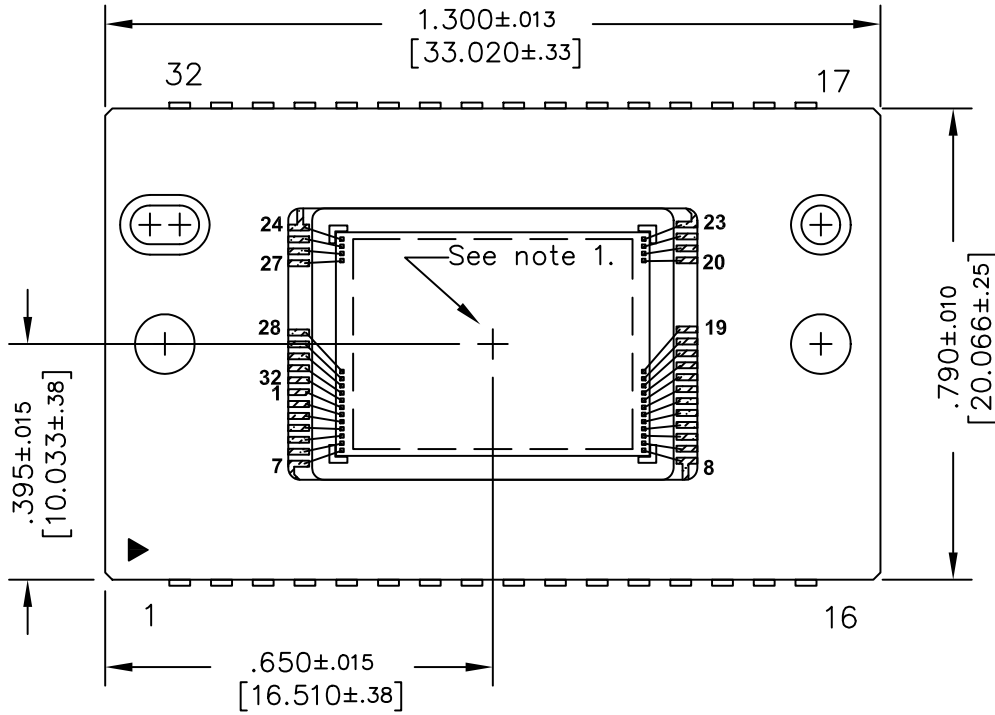


Dimensions in: Inches [mm]

DOCUMENT NUMBER:	98AON87287F	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
REFERENCE:		
DESCRIPTION:	CERAMIC DIP 32, 33.02x20.07	PAGE 1 OF 3

CERAMIC DIP 32, 33.02x20.07
CASE 125BD
ISSUE O

DATE 03 JUL 2014



NOTES:

1. CENTER OF IMAGE IS OFFSET FROM CENTER OF PACKAGE BY (0.00, 0.00)mm NOMINAL.
2. DIE IS ALIGNED WITHIN ± 1 DEGREE OF ANY PACKAGE CAVITY EDGE.

Dimensions in: Inches [mm]

DOCUMENT NUMBER:	98AON87287F	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
REFERENCE:		
DESCRIPTION:	CERAMIC DIP 32, 33.02x20.07	PAGE 2 OF 3

